## VLSI-SoC 2024: PhD Forum

## October 6-9, 2024 Tanger, Morocco https://vlsisoc2024.nl/

**Eligibility for Ph.D. Forum:** The author must have completed at least one year of a Ph.D. program. Past Ph.D. scholars who have defended their thesis in or after June 2023 are also encouraged to submit.

**Presentation:** Posters will be introduced in the Ph.D. Forum Session (two minute time slot, one slide) and next will be presented in a full one hour Poster Session.

**Publication:** Accepted posters will be given two pages in the informal proceedings.

**Grants for Ph.D. students:** VLSI-SoC 2024 will provide a limited number of travel grants through the Technical Committee TC-10 and WG-10.5 of the IFIP. Grants are intended to support students from emerging and underdeveloped countries (by UN classification), who cannot be fully supported by their institutions.

**How to Apply:** Submit a two-page extended abstract of your research work in PDF format. Send submissions via the Molesystems platform of VLSI-SoC 2024.

**Paper Format:** Papers should be compliant with the guidelines for regular papers.



VLSI-SoC 2024 is the 32th in a series of international conferences sponsored by IFIP WG 10.5, IEEE CEDA, and IEEE CASS, which explore the state-of-the-art in the areas of Very Large Scale Integration (VLSI) and System-on-Chip (SoC) design. The purpose of VLSI-SoC is to provide a forum to exchange ideas and showcase academic as well as industrial research in architectures, circuits, devices, design automation, verification, test, and security, within digital, analog, and mixed-signal systems. VLSI-SoC'24 will take place at hotel Barcelo, Tanger, Morocco, and it is organized by the Delft University of Technology.

VLSI-SoC 2024 will be held under the theme "SoCs for 5G Evolution and 6G" exploring the design and optimization challenges around 5G+6G communication systems and devices embedded systems, security, low power circuits, powered by CMOS and beyond CMOStechnologies.



The areas of interest include (but are not limited to) the following topics:

- Analog design: modelling, simulation, verification, and prototyping of analog, mixed-signal, RF, sensors, and IoT circuits
- Digital design: modelling, simulation, verification, and prototyping of circuits and systems, SoC, NoC, reconfigurable, IoT, and low-power architectures
- Design for AI hardware and emerging applications: unconventional computing, brain inspired computing, computation-in-memory, photonics, quantum, etc.
- EDA tools and methodologies for IC design
- Hardware Dependability: Design for testability, reliability, fault tolerance, security, safety, and variability
- Other specialized topics; e.g., Signal processing, Communications/ 5G/ 6G; Biomedical, MEMS, Cyberphysical systems, Power electronic devices and circuits, etc.

General Chairs: Said Hamdioui, Delft University of Technology (NL) & Anass El Haddadi, ENSA (MA)

Program Chairs: Hussam Amrouch, Technical University of Munich (DE) & Ioana Vatejelu, TIMA Grenoble (FR)

Tutorial Chair: Leticia M.B. Pöhls, RWTH Aachen University (DE) Special Session Chairs: Baker Mohammad, Khalifa University (AE) & Saraju Mohanty, University of North Texas (US)

Panel Chairs: Hassen Aziza, Aix-Marseille Université & Annachiara Ruospo, Politecnico di Torino (IT)

Awards Chairs: Fatih Ugurdag, Özyeğin University (TR) & Tiziana Margaria, University of Limerick (IE)

PHD Forum Chair: Florenc Demrozi, University of Stavanger (NO)

Publication Chairs: Moritz Fieback, Delft University of Technology (NL) & Anteneh Gebregiorgis, Delft University of Technology (NL)

Finance Chairs: Motta Taouil, Delft University of Technology (NL) & Carlo Galuzzi, Delft University of Technology (NL)

Web Chair: Heba Abunahla, Delft University of Technology (NL) & Mark van Beusekom, Delft University of Technology (NL)

Sponsoring Chairs: Mohamed Bouhorma, Abdelmalek Essaâdi University (AE) Local Arrangement Chairs: Nabila Harboul, Future Professionals Academy (NL) & Jaber El Bouhdidi, ENSA (MA)







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